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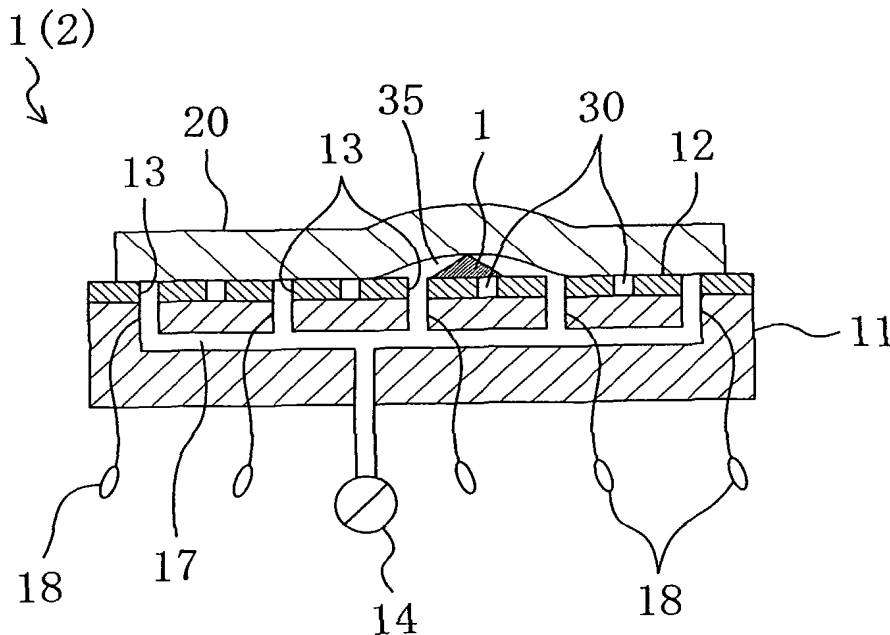
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(54) Title: SUBSTRATE ADSORPTION DEVICE AND SUBSTRATE BONDING DEVICE



(57) Abstract: A substrate  
adsorption device 1 includes: a  
stage 11 having an adsorption  
face 12 for holding a substrate  
20; a plurality of adsorption  
ports 13 formed in a region of  
the adsorption face 12 of the  
stage 11; and a vacuum pump 14  
connected to each adsorption port  
13 through an air discharge path 17.  
A pressure sensor 18 for detecting  
the pressure in the air discharge  
path 17 is provided, and a plurality  
of leak trenches 30 open to both  
the adsorption face 12 of the  
stage 11 and a side face of the  
stage 11 are formed in a region  
of the stage 11 except the region  
where the adsorption ports 13 are  
formed. With such a low-cost and  
simple structure, a foreign matter  
15, which is a factor of inviting  
damage to the substrate 20, is  
detected, to prevent damage to the  
substrate 20.

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